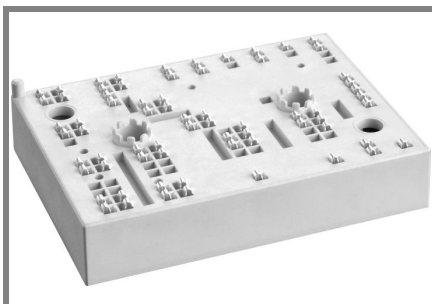


SKiiP 38AC12T4V1



MiniSKiiP[®]3

3-phase bridge inverter

SKiiP 38AC12T4V1

Features

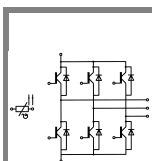
- Trench 4 IGBT's
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised file no. E63532

Typical Applications*

- Inverter up to 41 kVA
- Typical motor power 22 kW

Remarks

- V_{CEsat} , V_F = chip level value
- Case temp. limited to $T_C = 125^\circ\text{C}$ max. (for baseplateless modules $T_C = T_S$)
- product rel. results valid for $T_j \leq 150$ (recomm. $T_{op} = -40 \dots +150^\circ\text{C}$)
- For short circuit: Soft R_{Goff} recommended

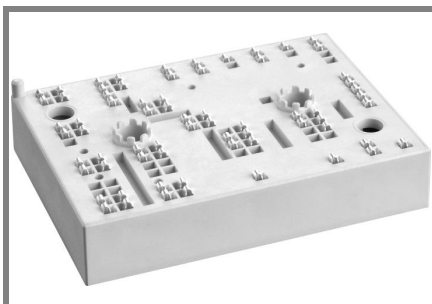


AC

Absolute Maximum Ratings		$T_S = 25^\circ\text{C}$, unless otherwise specified		
Symbol	Conditions	Values	Units	
IGBT				
V_{CES}	$T_j = 25^\circ\text{C}$	1200	V	
I_C	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	115	A
		$T_c = 70^\circ\text{C}$	93	A
I_{CRM}	$I_{CRM} = 3xI_{Cnom}$	300	A	
V_{GES}		± 20	V	
t_{psc}	$V_{CC} = 800\text{ V}; V_{GE} \leq 15\text{ V}; T_j = 150^\circ\text{C}$ $V_{CES} < 1200\text{ V}$	10	μs	
Inverse Diode				
I_F	$T_j = 175^\circ\text{C}$	$T_c = 25^\circ\text{C}$	99	A
		$T_c = 70^\circ\text{C}$	79	A
I_{FRM}	$I_{CRM} = 3xI_{Cnom}$	300	A	
I_{FSM}	$t_p = 10\text{ ms}; \sin$	$T_j = 150^\circ\text{C}$	548	A
Module				
$I_t(\text{RMS})$		160	A	
T_{vj}		-40...+150	$^\circ\text{C}$	
T_{stg}		-40...+125	$^\circ\text{C}$	
V_{isol}	AC, 1 min.	2500	V	

Characteristics		$T_S = 25^\circ\text{C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}, I_C = 4\text{ mA}$	5	5,8	6,5	V
I_{CES}	$V_{GE} = 0\text{ V}, V_{CE} = V_{CES}$	$T_j = 25^\circ\text{C}$		0,3	mA
		$T_j = 150^\circ\text{C}$		0,7	0,8
V_{CE0}			0,8	0,9	V
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$	10	11	$\text{m}\Omega$
		$T_j = 150^\circ\text{C}$	15	16	$\text{m}\Omega$
$V_{CE(sat)}$	$I_{Cnom} = 100\text{ A}, V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}_{chiplev.}$	1,8	2	V
		$T_j = 150^\circ\text{C}_{chiplev.}$	2,2	2,4	V
C_{ies}	$V_{CE} = 25, V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	6,2		nF
C_{oes}			0,41		nF
C_{res}			0,35		nF
Q_G	$V_{GE} = -8\dots+15\text{ V}$		565		nC
R_{Gint}	$T_j = 25^\circ\text{C}$		7,5		Ω
$t_{d(on)}$	$R_{Gon} = 1\ \Omega$ $di/dt = 2080\text{ A}/\mu\text{s}$	$V_{CC} = 600\text{ V}$ $I_C = 100\text{ A}$	160		ns
t_r			45		ns
E_{on}	$R_{Goff} = 1\ \Omega$ $di/dt = 1240\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$ $V_{GE} = \pm 15\text{ V}$	13,7		mJ
$t_{d(off)}$			395		ns
t_f			73		ns
E_{off}			9,7		mJ
$R_{th(j-s)}$	per IGBT		0,48		K/W

SKiiP 38AC12T4V1



MiniSKiiP[®]3

3-phase bridge inverter

SKiiP 38AC12T4V1

Features

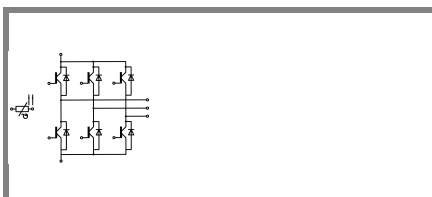
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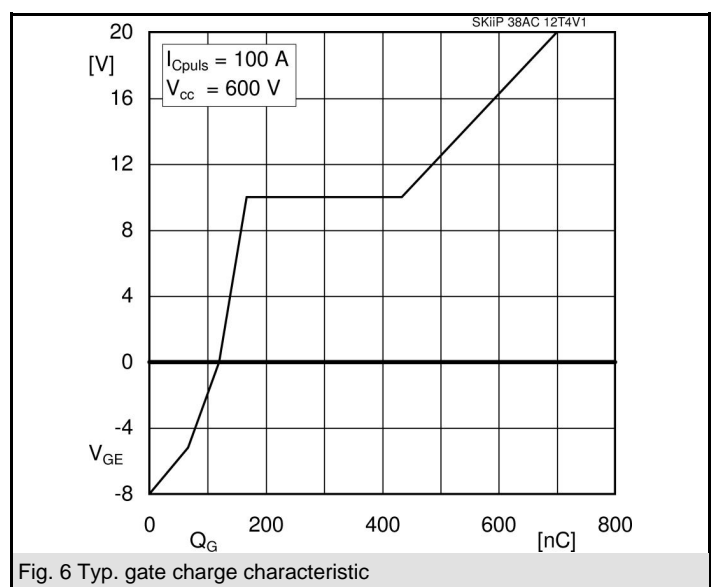
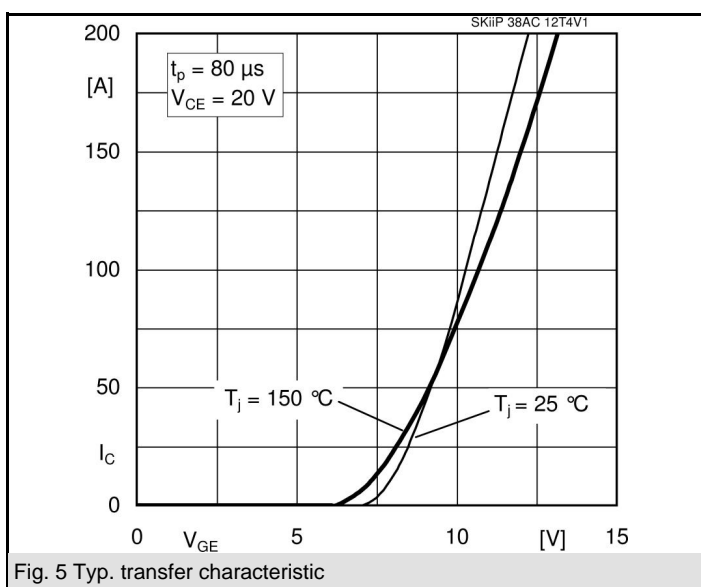
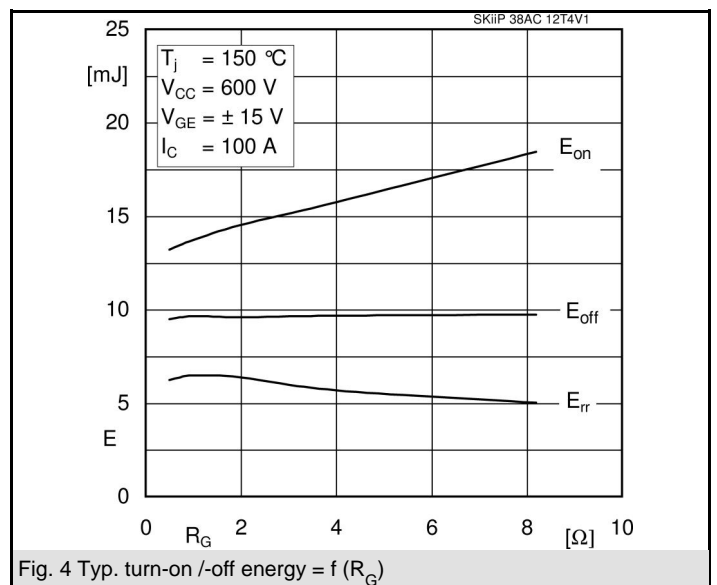
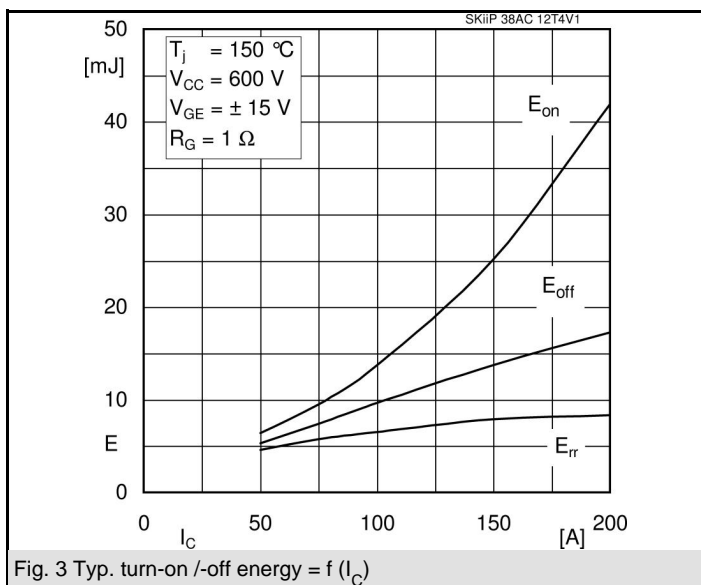
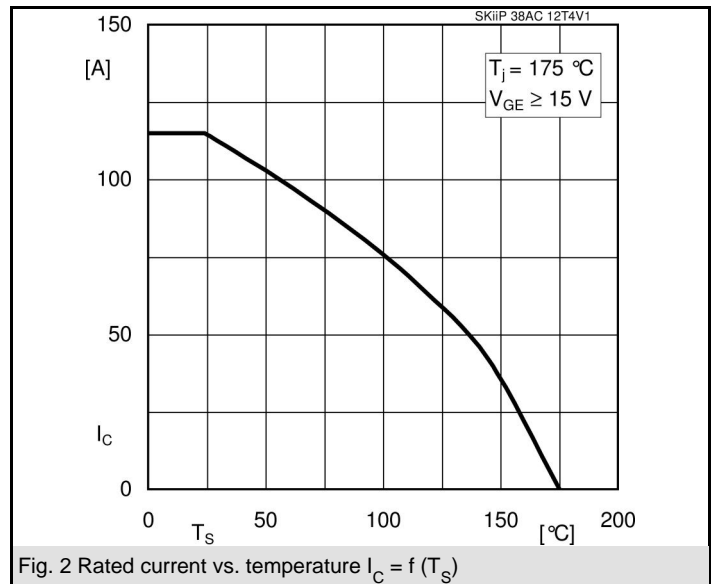
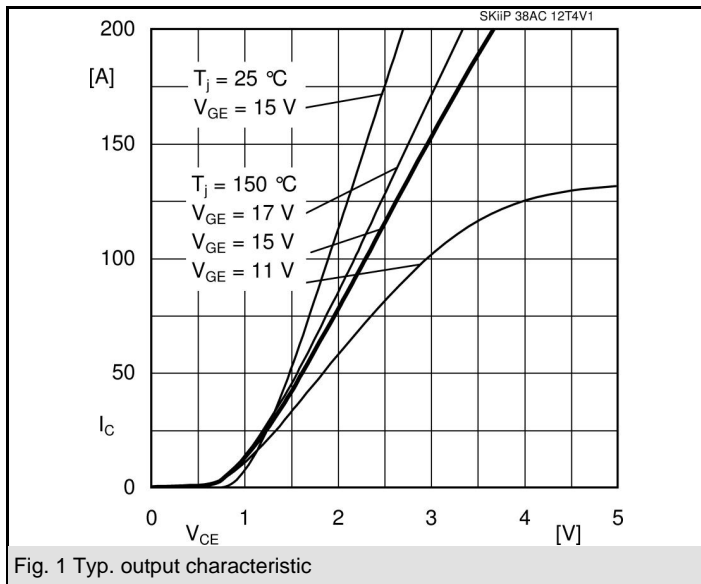


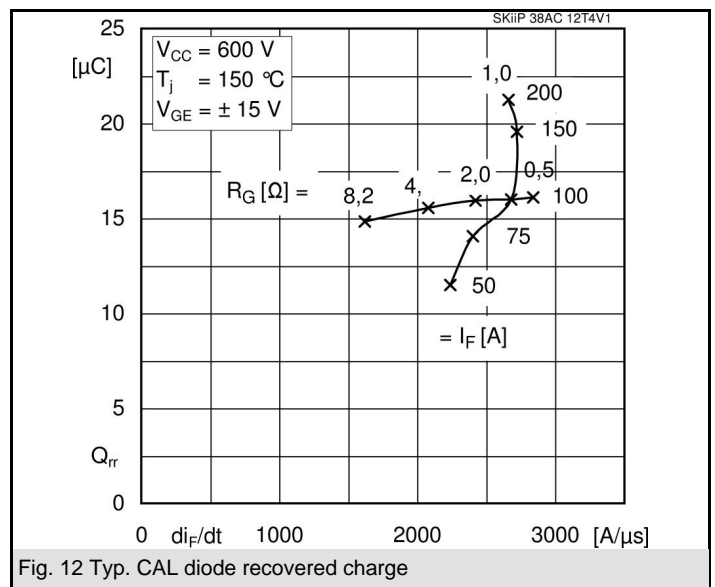
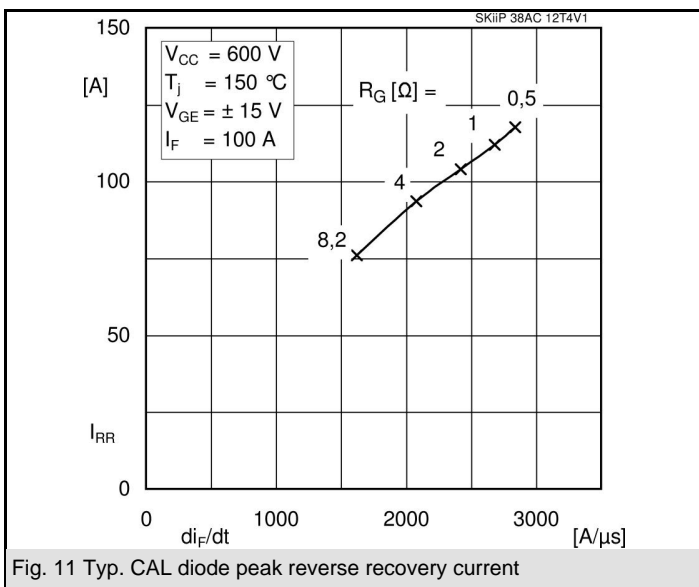
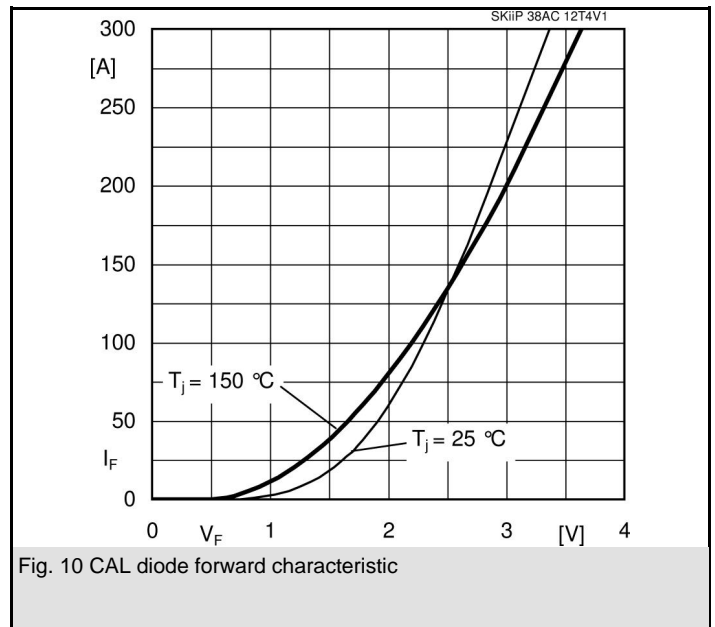
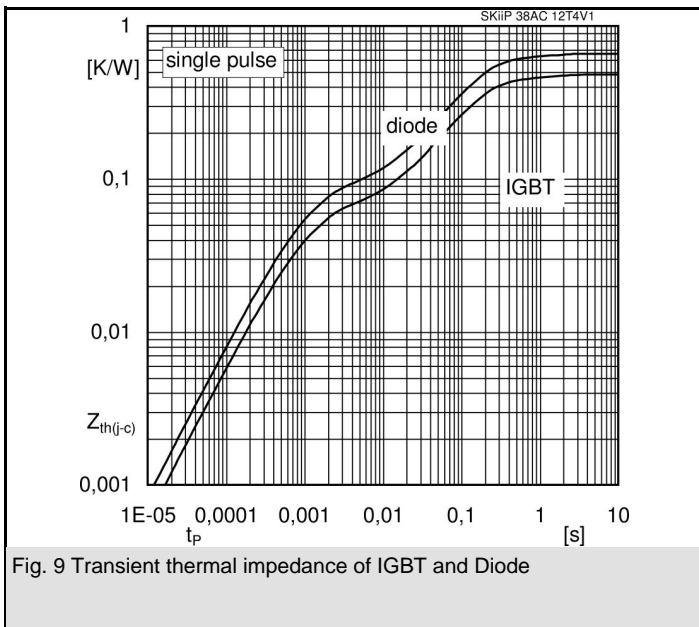
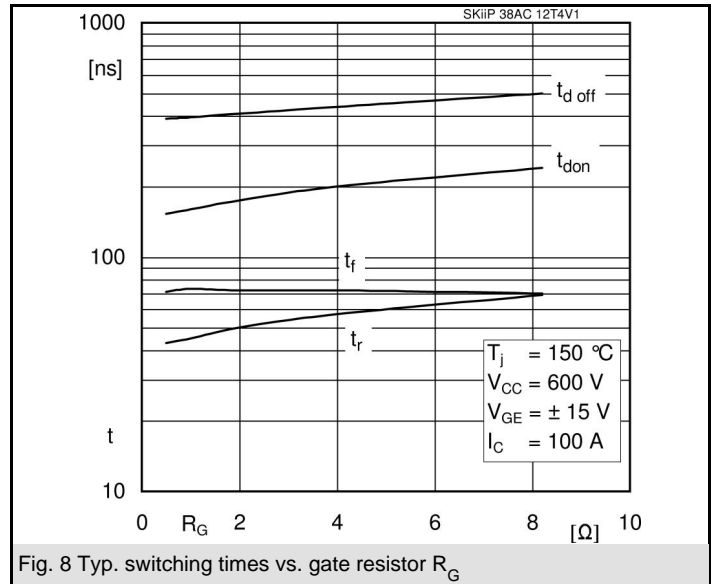
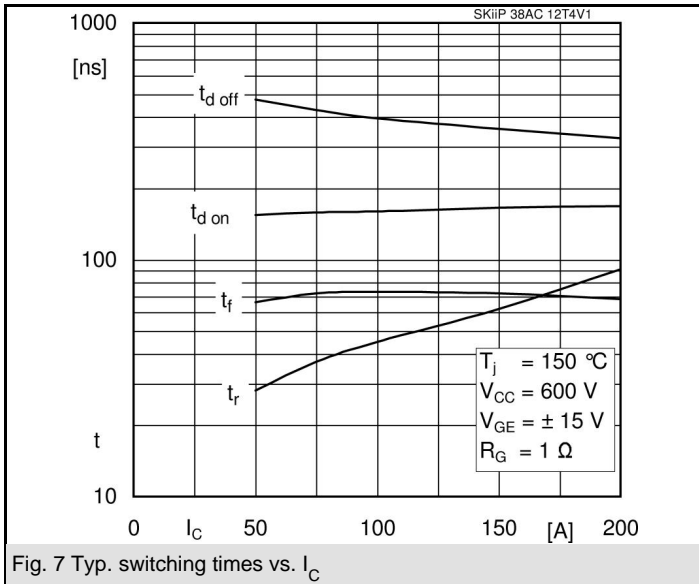
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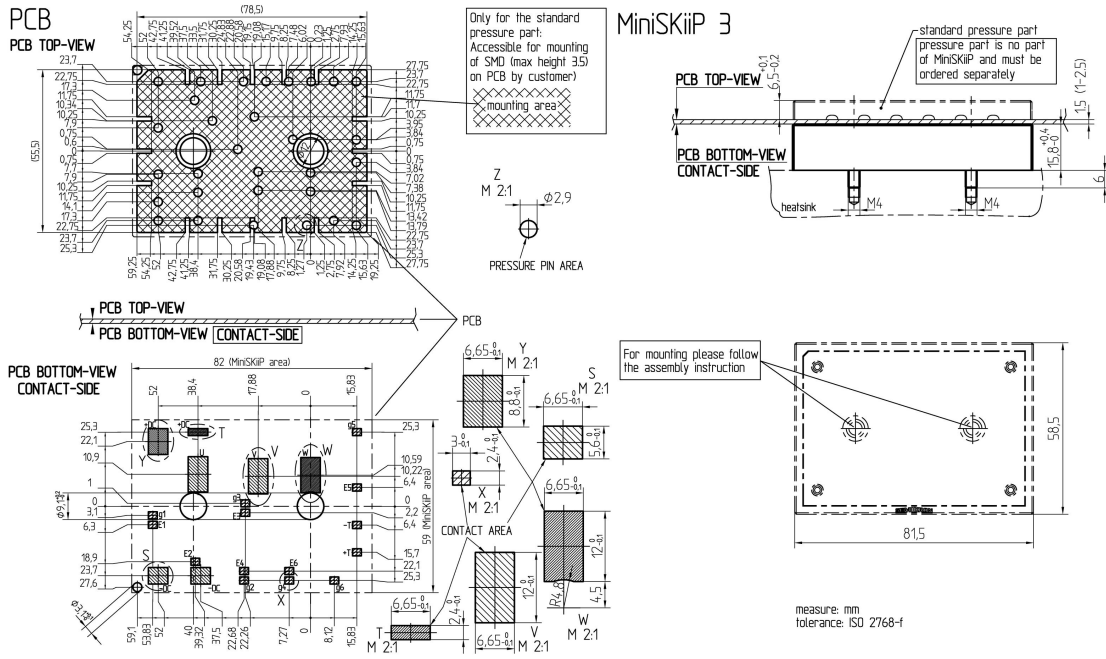
Characteristics						
Symbol	Conditions	min.	typ.	max.	Units	
Inverse Diode						
$V_F = V_{EC}$	$I_{Fnom} = 100 \text{ A}; V_{GE} = 15 \text{ V}$		$T_j = 25^\circ\text{C}_{\text{chiplev.}}$	2,2	2,5	V
			$T_j = 150^\circ\text{C}_{\text{chiplev.}}$	2,1	2,45	V
V_{F0}			$T_j = 25^\circ\text{C}$	1,3	1,5	V
			$T_j = 150^\circ\text{C}$	0,9	1,1	V
r_F			$T_j = 25^\circ\text{C}$	9	10	m Ω
			$T_j = 150^\circ\text{C}$	12	13,5	m Ω
I_{RRM}	$I_F = 100 \text{ A}$	$T_j = 125^\circ\text{C}$		112	A	
Q_{rr}	$di/dt = 2680 \text{ A}/\mu\text{s}$			16	μC	
E_{rr}	$V_{GE} = \pm 15 \text{ V}$			6,5	mJ	
$R_{th(j-s)}$	per diode		0,66		K/W	
M_s	to heat sink	2		2,5	Nm	
w			95		g	
Temperature sensor						
R_{ts}	3%, $T_r = 25^\circ\text{C}$		1000		Ω	
R_{ts}	3%, $T_r = 100^\circ\text{C}$		1670		Ω	

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.

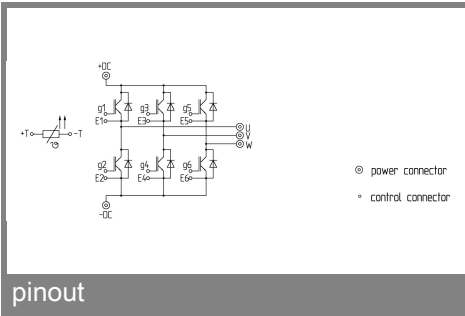






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case



pinout